

NVMFS6B05NLT1G-VB Datasheet

N-Channel 100V (D-S) MOSFET

PRODUCT SUMMARY

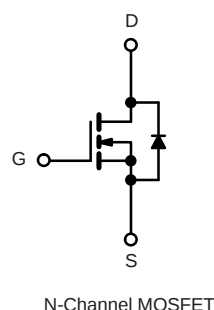
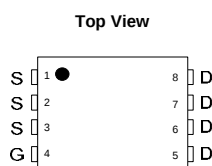
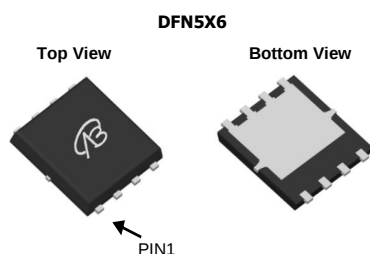
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A) ^a
100	0.005at $V_{GS} = 10$ V	105
	0.006at $V_{GS} = 4.5$ V	95

FEATURES

- 175 °C Junction Temperature
- SGT technology Power MOSFET
- Material categorization:



RoHS
COMPLIANT



ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

Parameter	Symbol	Limit	Unit
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_J = 175$ °C) ^b	$T_C = 25$ °C	I_D	105
	$T_C = 100$ °C		60 ^a
Pulsed Drain Current	I_{DM}	315	A
Continuous Source Current (Diode Conduction)	I_S	170 ^a	
Avalanche Current	I_{AS}	60	
Single Avalanche Energy (Duty Cycle ≤ 1 %)	$L = 0.1$ mH E_{AS}	110	mJ
Maximum Power Dissipation	$T_C = 25$ °C	P_D	136
	$T_A = 25$ °C		3 ^b , 8.3 ^{b, c}
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	R_{thJA}	$t \leq 10$ sec	15	°C/W
		Steady State	40	
Maximum Junction-to-Case	R_{thJC}	0.85	1.1	

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

c. $t \leq 10$ s.

SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	100			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1	2	3	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30V, V _{GS} = 0 V			1	μA
		V _{DS} = 30V, V _{GS} = 0 V, T _J = 125 °C			50	
		V _{DS} = 30V, V _{GS} = 0 V, T _J = 175 °C			250	
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	60			A
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A		0.005		Ω
		V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.008		
		V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C		0.010		
		V _{GS} = 4.5 V, I _D = 35 A		0.006		
Forward Transconductance ^b	g _{fs}	V _{DS} = 15 V, I _D = 20 A		60		S
Dynamic						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz		11000		pF
Output Capacitance	C _{oss}			470		
Reverse Transfer Capacitance	C _{rss}			225		
Total Gate Charge ^c	Q _g	V _{DS} = 100 V, V _{GS} = 10 V, I _D = 50 A		80	70	nC
Gate-Source Charge ^c	Q _{gs}			17		
Gate-Drain Charge ^c	Q _{gd}			12		
Turn-On Delay Time ^c	t _{d(on)}	V _{DD} = 100 V, R _L = 0.6 Ω I _D ≅ 50 A, V _{GEN} = 10 V, R _g = 2.5 Ω		19	27	ns
Rise Time ^c	t _r			15	25	
Turn-Off Delay Time ^c	t _{d(off)}			35	50	
Fall Time ^c	t _f			20	30	
Source-Drain Diode Ratings and Characteristics (T _C = 25 °C)						
Pulsed Current	I _{SM}				315	A
Diode Forward Voltage	V _{SD}	I _F = 20 A, V _{GS} = 0 V		1	1.5	V
Reverse Recovery Time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs		4	135	ns

Notes:

- a. For design aid only; not subject to production testing.
 b. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
 c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

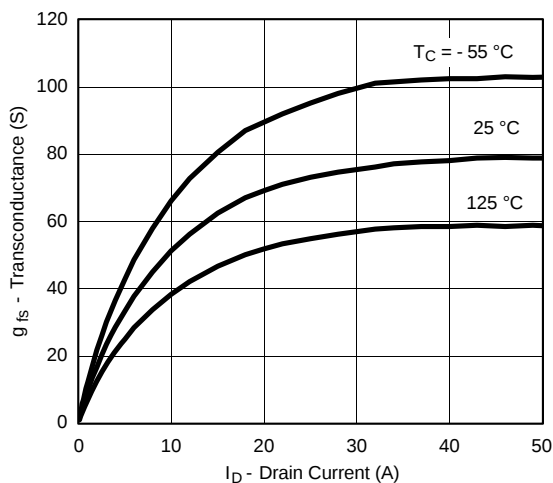
TYPICAL CHARACTERISTICS (25 °C unless noted)



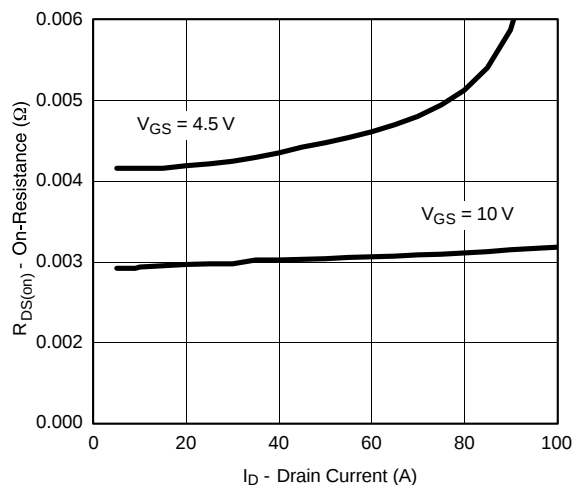
Output Characteristics



Transfer Characteristics



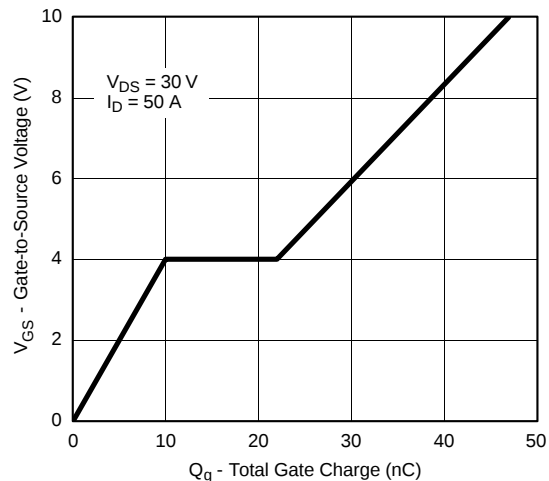
Transconductance



On-Resistance vs. Drain Current



Capacitance

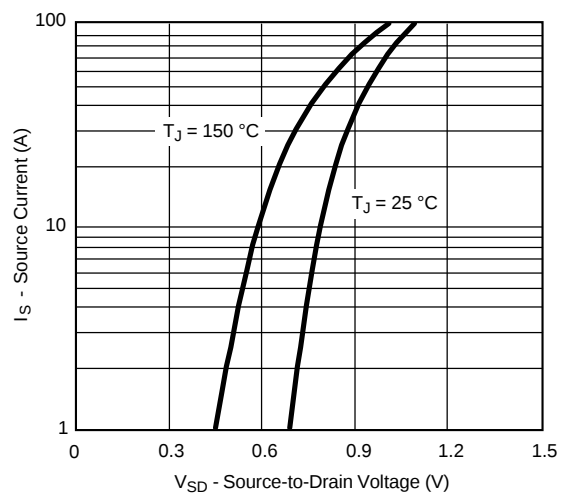


Gate Charge

TYPICAL CHARACTERISTICS (25 °C unless noted)



On-Resistance vs. Junction Temperature

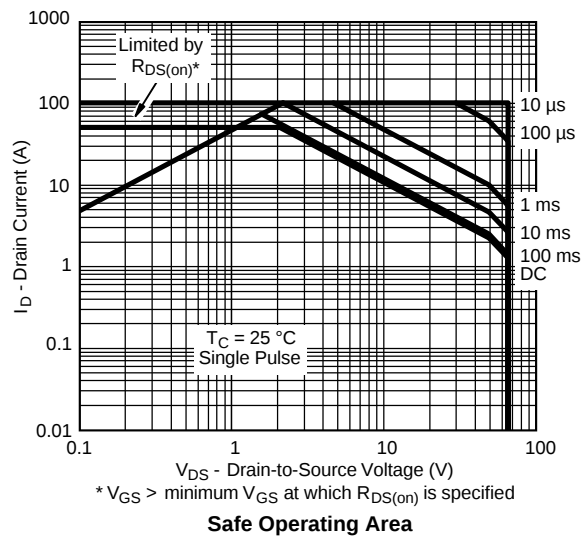


Source-Drain Diode Forward Voltage

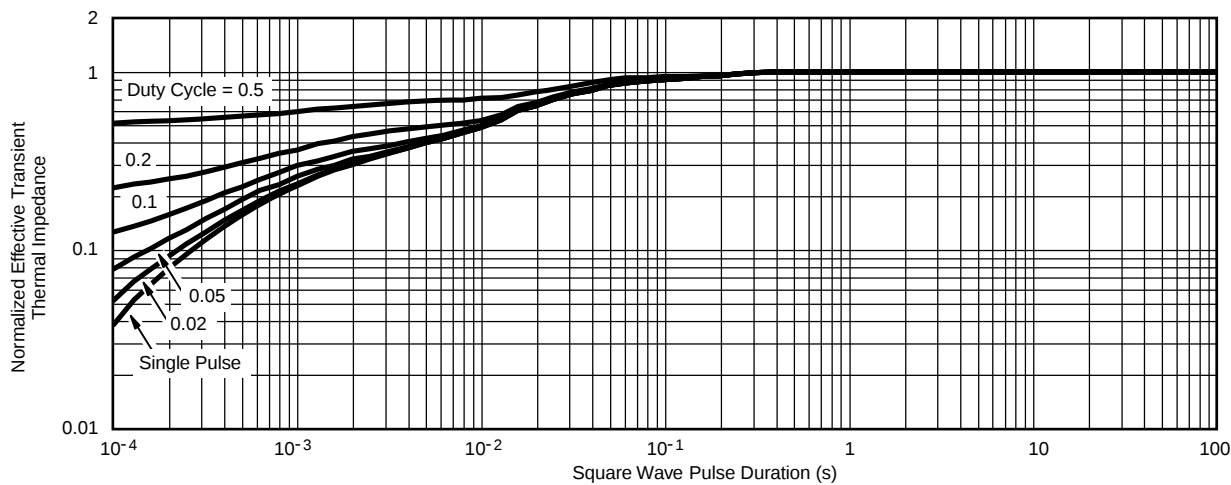
THERMAL RATINGS



Maximum Drain Current vs. Ambient Temperature



Safe Operating Area



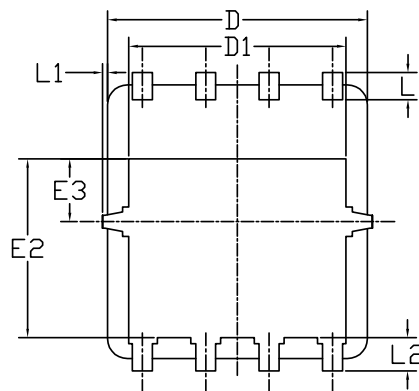
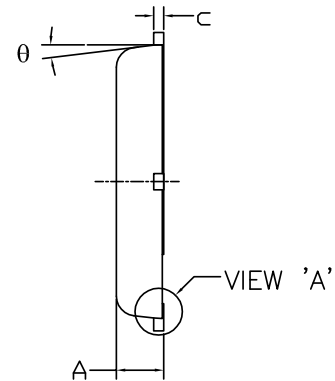
Normalized Thermal Transient Impedance, Junction-to-Case

Technical drawing of a square flange with dimensions and a table.

Dimensions shown in the drawing:

- $\varnothing$ (Diameter symbol)
- 0.05
- $\textcircled{M}$ (Material symbol)
- b (Distance from center to mounting hole center)
- e (Distance between mounting holes)
- E (Total thickness)
- E_1 (Inner thickness)

Symbol	Value	Unit
$\varnothing$	10	mm
0.05	0.05	mm
$\textcircled{M}$	M10	mm
b	25	mm
e	50	mm
E	10	mm
E_1	5	mm



VIEW 'A'
(SCALE 5:1)

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.85	0.95	1.00	0.033	0.037	0.039
A1	0.00	----	0.05	0.000	----	0.002
b	0.30	0.40	0.50	0.012	0.016	0.020
c	0.15	0.20	0.25	0.006	0.008	0.010
D	5.10	5.20	5.30	0.201	0.205	0.209
D1	4.25	4.35	4.45	0.167	0.171	0.175
E	5.45	5.55	5.65	0.215	0.219	0.222
E1	5.95	6.05	6.15	0.234	0.238	0.242
E2	3.525	3.625	3.725	0.139	0.143	0.147
E3	1.175	1.275	1.375	0.046	0.050	0.054
e	1.27 BSC			0.050 BSC		
L	0.45	0.55	0.65	0.018	0.022	0.026
L1	0	----	0.15	0	----	0.006
L2	0.68 REF			0.027 REF		
θ	0°	----	10°	0°	----	10°

NOTE

- NOTE
1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
2. CONTROLLING DIMENSION IS MILLIMETER.
CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

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